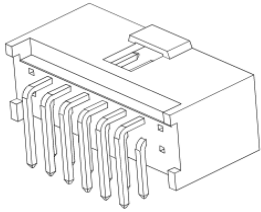


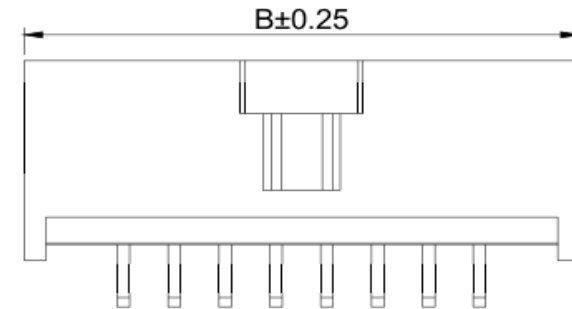
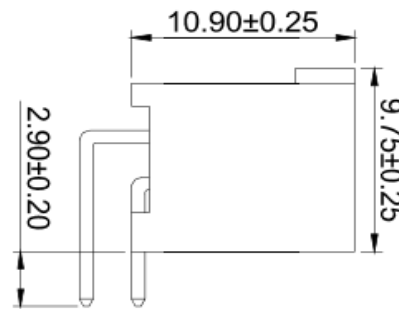
EDCON-COMPONENTS



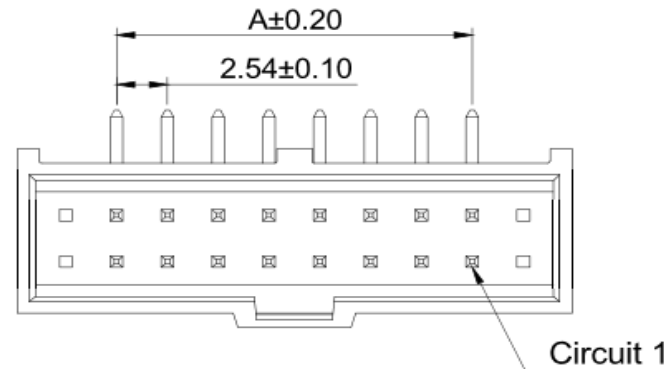
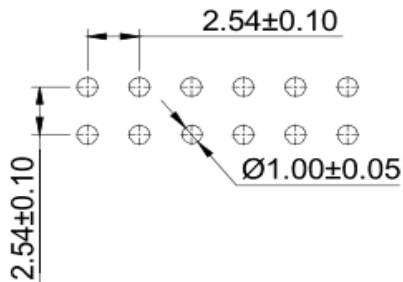
Technical Description

Curent Rating:	3,0A
Voltage Rating:	250V AC,DC
Contact Resistance:	20mΩ max.
Withstanding Voltage:	1500VAC/ DC
Insulation Resistance:	1000MΩ Min
Operating Temperature:	.-40°C to + 105°C
Contact Material:	Brass
Contact Plating:	like Ordering
Insulator Material:	PBT + 30%G.F. UL94V-0
Glow-Wire Test	IEC60335-1

Drawing



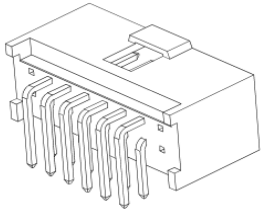
PCB Layout (mm)



Wire to Board Connector (Wafer) Right Angle Pin Dual Row	
Part No.:	T68N365
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 4	

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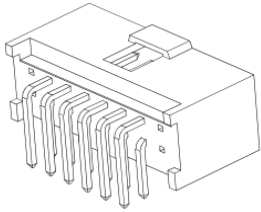
Dimension (mm)

No Pin	A	B	No Pin	A	B
2x2	5,08	9,96	2x30	76,20	81,08
2x3	7,62	12,50	2x31	78,74	83,62
2x4	10,16	15,04	2x32	81,28	86,16
2x5	12,70	17,58	2x33	83,82	88,70
2x6	15,24	20,12	2x34	86,36	91,24
2x7	17,78	22,66			
2x8	20,32	25,20			
2x9	22,86	27,74			
2x10	25,40	30,28			
2x11	27,94	32,82			
2x12	30,48	35,36			
2x13	33,02	37,90			
2x14	35,56	40,44			
2x15	38,10	42,98			
2x16	40,64	45,52			
2x17	43,18	48,06			
2x18	45,72	50,60			
2x19	48,26	53,14			
2x20	50,80	55,68			
2x21	53,34	58,22			
2x22	55,88	60,76			
2x23	58,42	63,30			
2x24	60,96	65,84			
2x25	63,50	68,38			
2x26	66,04	70,92			
2x27	68,58	73,46			
2x28	71,12	76,00			
2x29	73,66	78,54			

Wire to Board Connector (Wafer) Right Angle Pin Dual Row	
Part No.:	T68N365
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.		2 from 4

EDCON-COMPONENTS



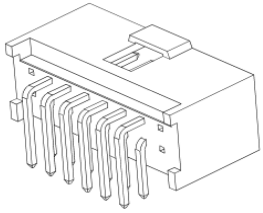
Ordering Informations

Serie	No. Of Position	Contact Plating	Contact Material	Color of Body	Special Function	Special Function	ROHS	Packing		
T68N365	04	GF	BR	BK	N	N	R	BU		

04= 2x2Pos.	TN= tinned	BR= Brass		N= No Function	N= No Function	R= ROHS Conform	BU= Bulk-Ware
2x2 ~ 2x34Pos.	GF= Gold Flash 0,25~0,5µ		BK= Black			N= NON ROHS Conform	TU= Tube Packing
	GA= Gold 3µ						TC= Tube w. Cap Packing
	GB= Gold 5µ						TR= Tape/Reel Packing w. Cap w. needed
	GC= Gold 10µ						IV= Individual Packing
	GD= Gold 15µ						
	GE= Gold 30µ						
	SA= Selectiv Gold 3µ						
	SB= Selectiv Gold 5µ						
	SC= Selectiv Gold 10µ						
	SD= Selectiv Gold 15µ						
	SE= Selectiv Gold 30µ						

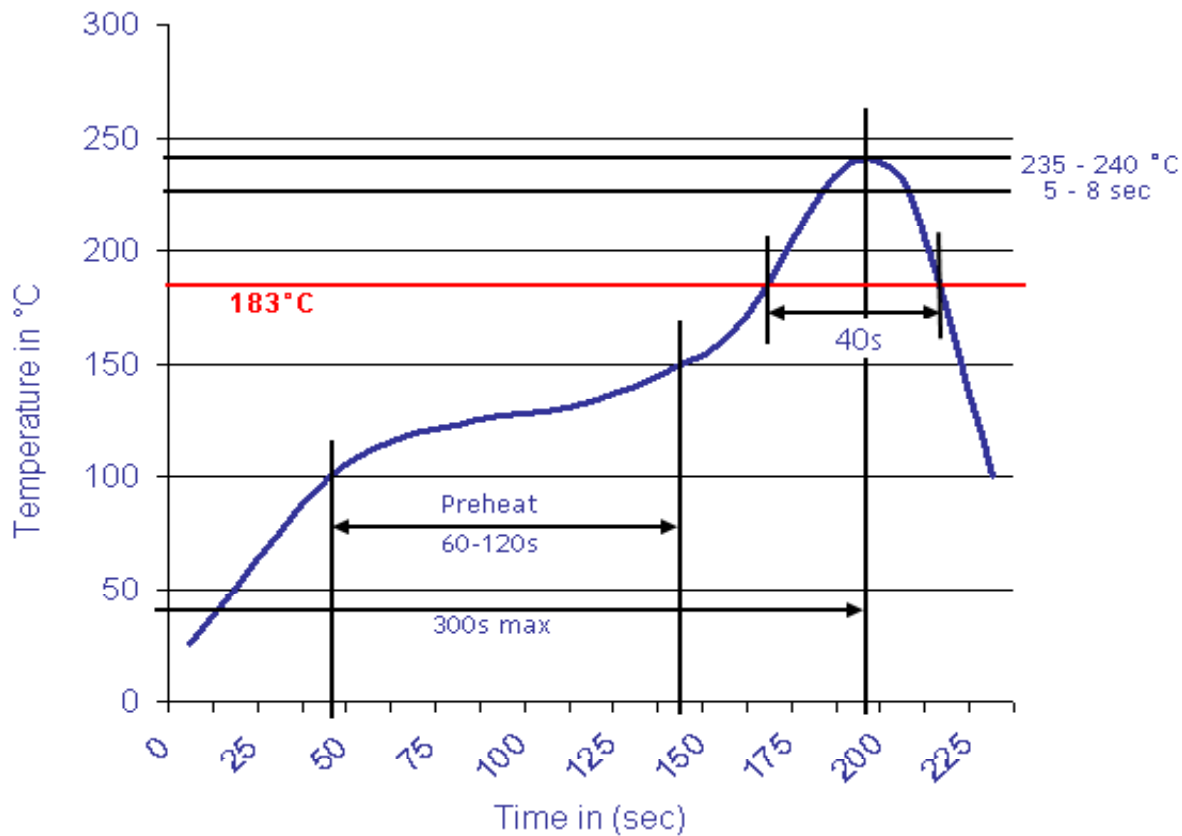
Wire to Board Connector (Wafer) Right Angle Pin Dual Row	
Part No.:	T68N365
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



Wire to Board Connector (Wafer) Right Angle Pin Dual Row	
Part No.:	T68N365
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.		4 from 4